Title (en)

MULTI-STEP IMAGE ALIGNMENT METHOD FOR LARGE OFFSET DIE-DIE INSPECTION

Title (de)

BILDAUSRICHTUNGSVERFAHREN IN MEHREREN SCHRITTEN FÜR EINE GROSSE OFFSET-CHIP-CHIP-INSPEKTION

Title (fr)

PROCÉDÉ D'ALIGNEMENT D'IMAGE À ÉTAPES MULTIPLES POUR INSPECTION ENTRE PUCES À DÉCALAGE IMPORTANT

Publication

EP 3698322 A1 20200826 (EN)

Application

EP 18867402 A 20181019

Priority

- US 201762575304 P 20171020
- US 201816160515 A 20181015
- US 2018056600 W 20181019

Abstract (en)

[origin: US2019122913A1] A die-die inspection image can be aligned using a method or system configured to receive a reference image and a test image, determine a global offset and rotation angle from local sections on the reference image and test image, and perform a rough alignment de-skew of the test image prior to performing a fine alignment.

IPC 8 full level

G06T 7/33 (2017.01); **G06T 7/00** (2017.01); **H01L 21/66** (2006.01)

CPC (source: EP KR US)

G06T 3/14 (2024.01 - EP US); **G06T 3/20** (2013.01 - US); **G06T 3/608** (2013.01 - US); **G06T 7/001** (2013.01 - EP KR US); **G06T 7/337** (2016.12 - EP KR US); **G06T 7/74** (2016.12 - US); **H01L 21/67288** (2013.01 - US); **H01L 22/12** (2013.01 - KR); **H01L 22/20** (2013.01 - KR); G06T 2207/20016 (2013.01 - EP US); G06T 2207/20021 (2013.01 - US); G06T 2207/20056 (2013.01 - EP US); G06T 2207/20081 (2013.01 - EP US); G06T 2207/30148 (2013.01 - EP KR US)

Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

US 10522376 B2 20191231; **US 2019122913 A1 20190425**; CN 111164646 A 20200515; EP 3698322 A1 20200826; EP 3698322 A4 20210602; JP 2021500740 A 20210107; JP 7170037 B2 20221111; KR 102412022 B1 20220622; KR 20200060519 A 20200529; TW 201928541 A 20190716; TW I774863 B 20220821; WO 2019079658 A1 20190425

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